



Re-Engineering Engineering

For AI Chip Design, Verification and Optimization

Vikas Gautam, VP Engineering
DVCON India, September 2025

Legal Disclosure

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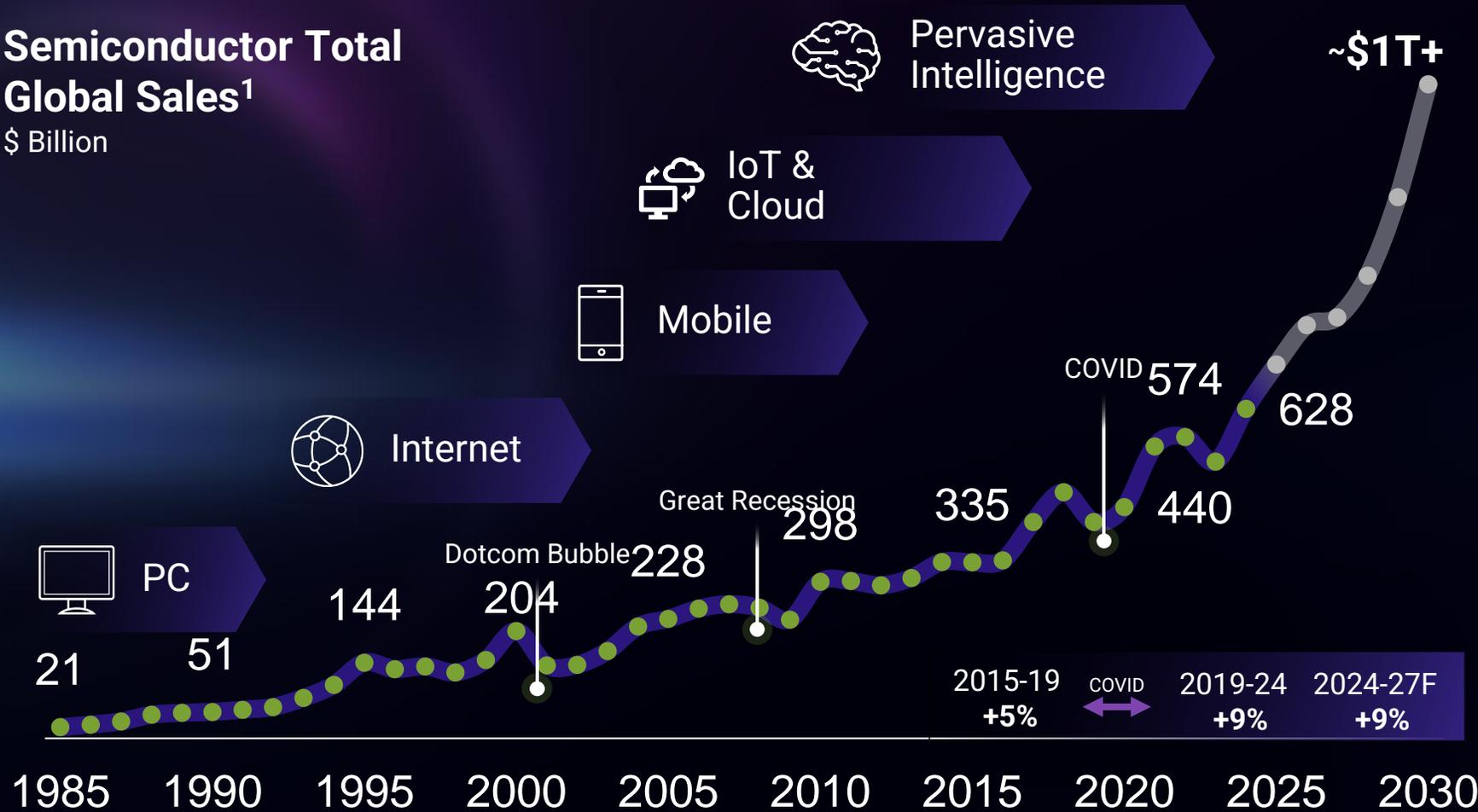
Agenda

- Industry Trends
- 2024 Recap and More Challenges Emerge
- Technology Evolution by Example – Microsoft
- Use Cases
 - Driving Reconfigurability & Modularity
 - EP=Ready Hardware
 - Driving Verification Requirements
- AI for Productivity Improvements
- Outlook: Where do we go from here?

A new era of semi demand acceleration

Semiconductor Total Global Sales¹

\$ Billion



Explosion in demand for AI chips²

Potential **\$500B+** (~30% CAGR) in xPU revenues by 2029

1. Sources: WSTS (actuals); Forecasts based on WSTS, Gartner, Tech Insights, IBS, Semi Sample

2. Sources: New Street Research, AMD, Nvidia, TSMC, Intel, Goldman Sachs

Impact of the latest AI trends

Energy



4GW
powered data
centers

Source: Tech Crunch, Meta

AI Models



50T
50 trillion tokens
per month

Source: Microsoft Azure, 2025

Agents



\$155B
agentic spending
by 2030

Source: Bank of America, 2025

Economy



15%
boost to global
GDP by 2035

Source: PWC, 2025

Recap from Last Year's Discussion

Google & Synopsys

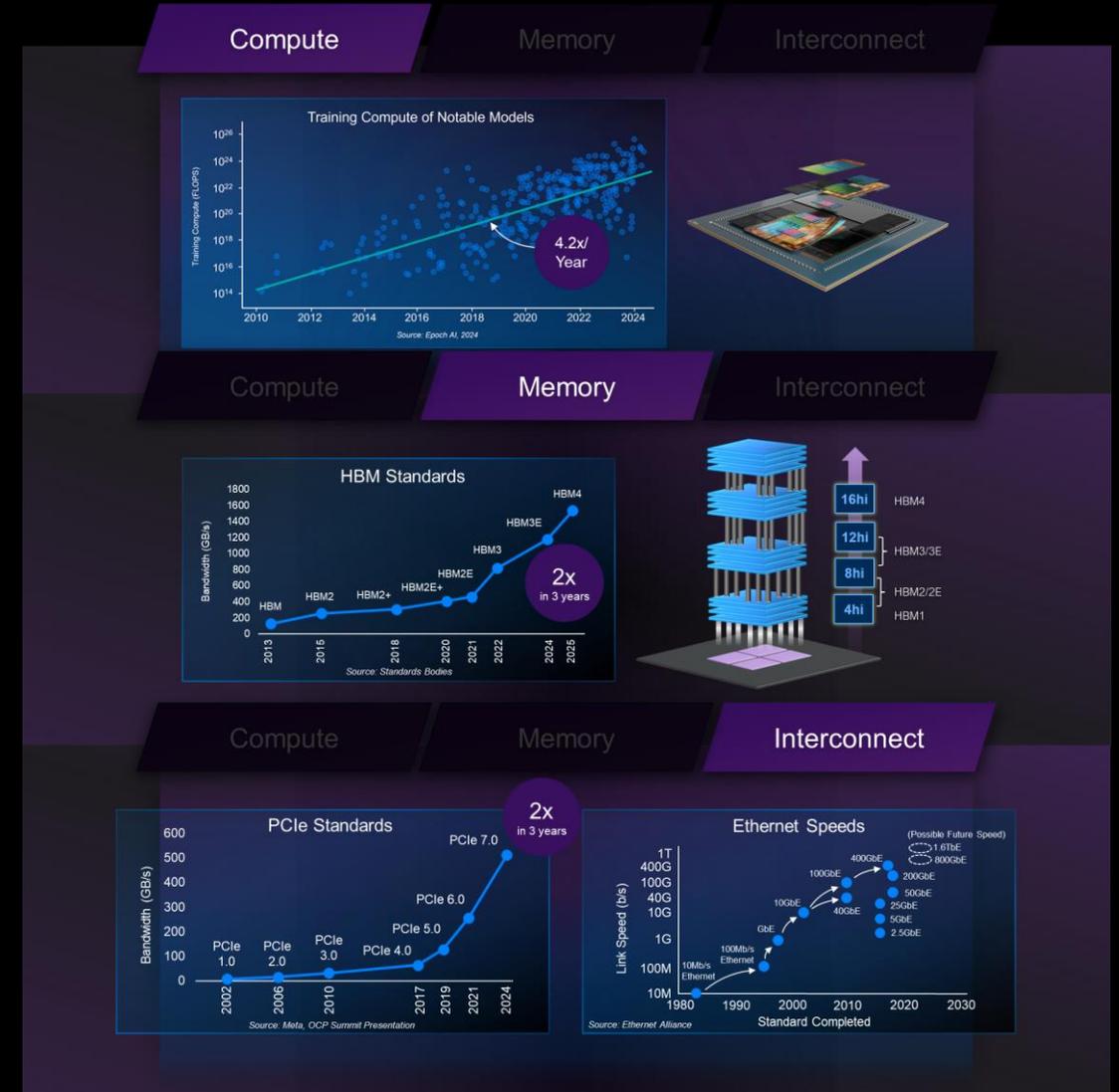
Recap from Last Year: AI & Google

Three Drivers: Compute, Memory and Interconnect

Era of Pervasive Intelligence



Semiconductors Appear Everywhere

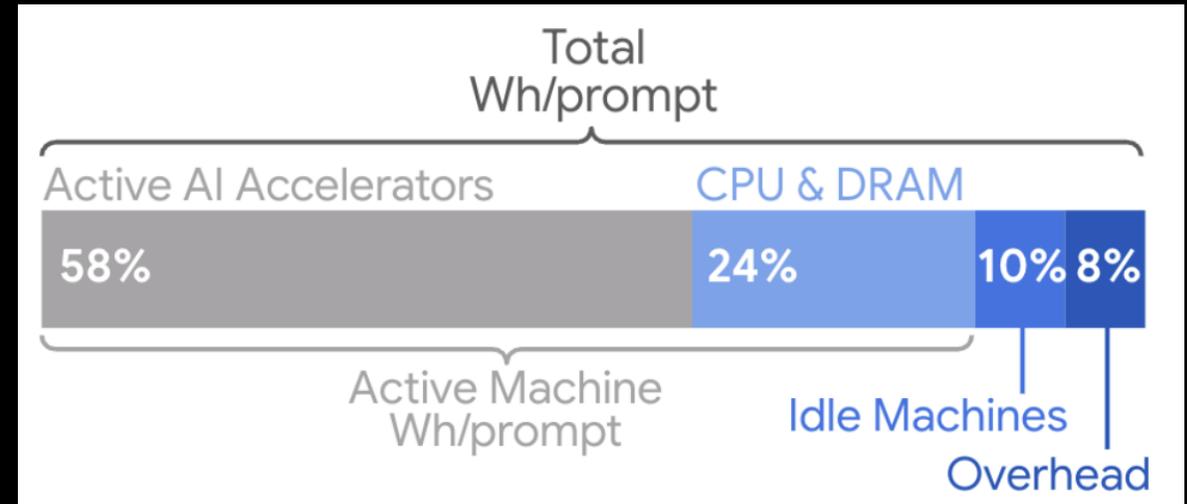


And The Challenges Only Grow!

And Accelerated Low Power Demands from Datacenters

Gemini Text Prompt: 9 seconds of watching TV ...

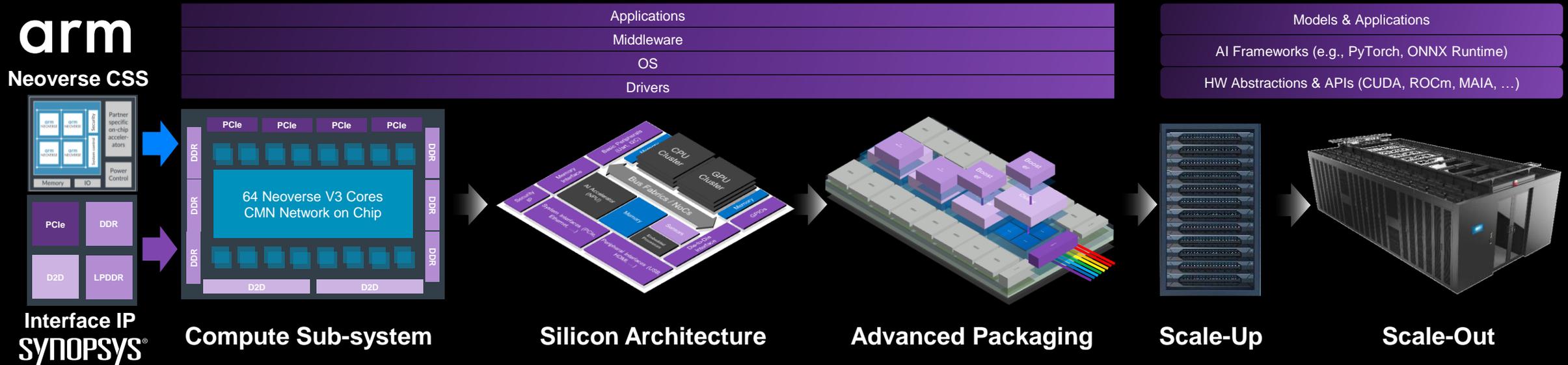
*The median Gemini Apps text prompt uses **0.24 watt-hours (Wh)** of energy, emits **0.03 grams of carbon dioxide equivalent (gCO₂e)**, and consumes **0.26 milliliters (or about five drops) of water** — figures that are substantially lower than many public estimates. The per-prompt energy impact is **equivalent to watching TV for less than nine seconds.***



[Source: How much energy does Google's AI use? We did the math](#)

AI Workloads Drive Datacenter-level Optimization & Verification

From compute and interface IP to running AI workloads



NoC configuration?

How to get to lowest power?

What is the best Chiplet partitioning?

Workload-specific AI/Compute architectures?

How to ensure reliability throughout lifecycle?

How to get 17% more performance?

Validate AI Workloads on IP and SoC?

How to validate cache coherency?

Accelerating IP Re-use at Higher Hardware/Software Complexity

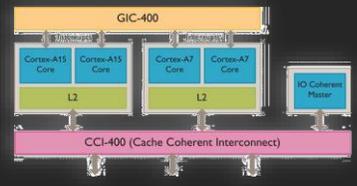
1998
Arm 9



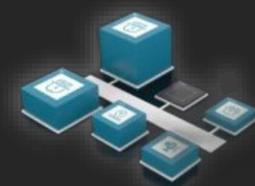
2007
Arm Cortex A9



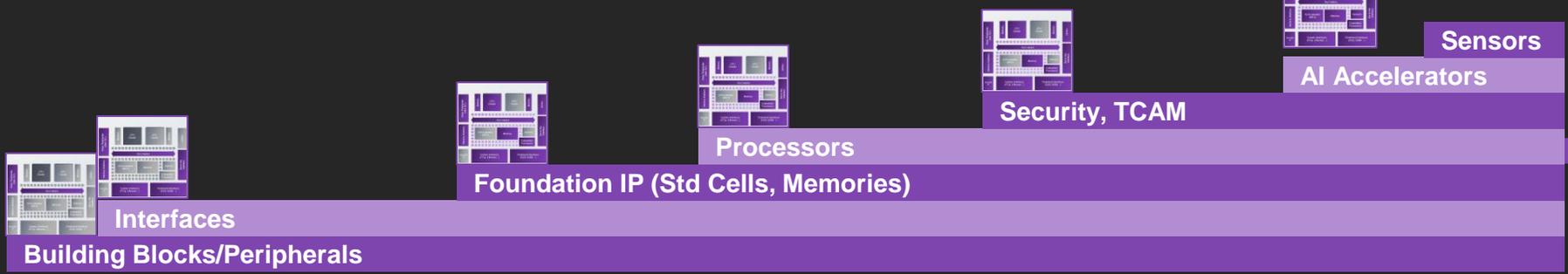
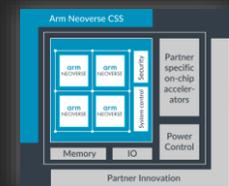
2011
BigLITTLE



2017
Arm DynamIQ



2023
Arm CSS N2



2000

2010

2020

Technology Evolution by Example

Microsoft & Synopsys at DVCON US 2025

The KPI for the World's Computer and AI Factories

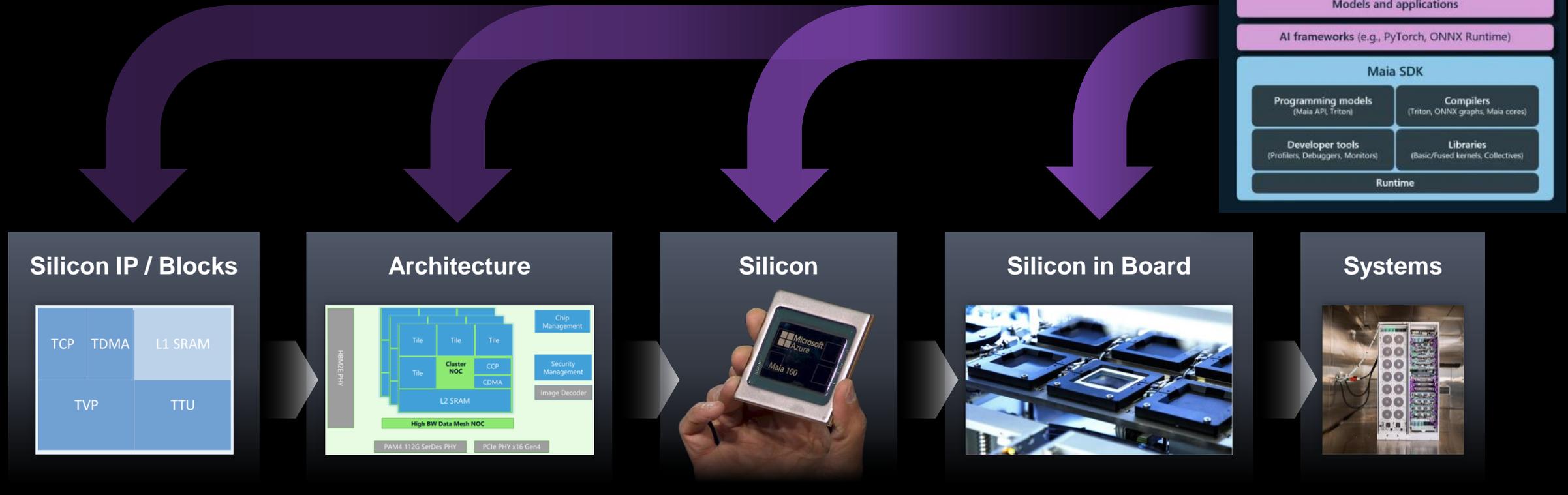
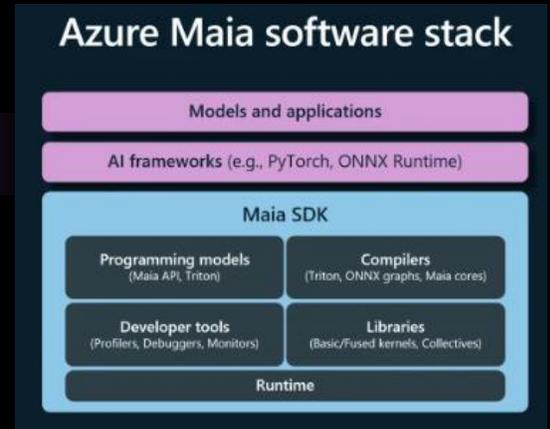
Performance / \$
Performance / Watt



Use Cases are Driven by AI Workloads

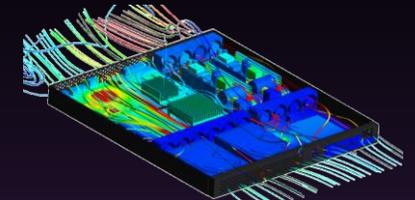
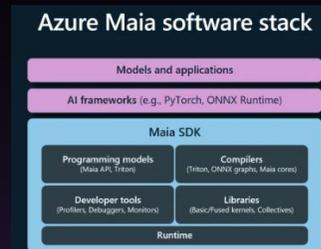
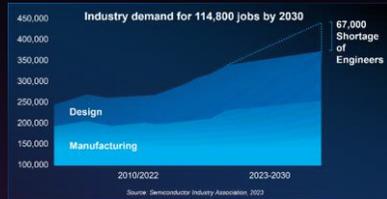
Application of AI Workloads needs to shift left as far as possible

WORKLOADS



Many Use Cases: IP in System Validation, Performance Validation, Compliance, Functional Verification, RTL Regressions, Early Software Bring-up, Hardware/Software Validation, Early Performance and Low Power Analysis, Reliability, Security, Design for Test, Silicon Lifecycle Management

Microsoft's Asks to the Industry - Capabilities



AI for Design

Early Software Workloads

Modular Approaches & Distributed Systems

Fabrics

End to End Thermal

Need 2x end-to-end efficiency in the next 2-3 years

We are just scratching the surface

Performance & Capacity of Engines

Analysis and optimization

Brute force approaches become ineffective

Multi-chiplet, Multi-SoC

High bandwidth
Low power scalable
configurable

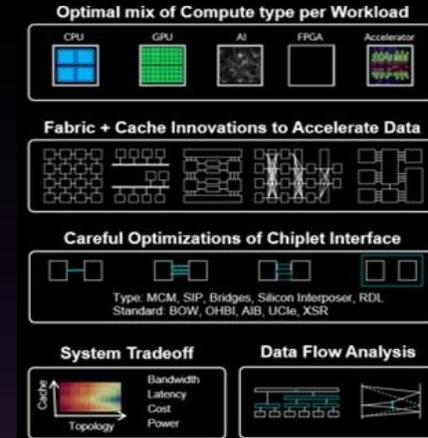
Supporting multi-chiplet design

Capabilities exist

Not yet fully integrated into the silicon design Flow

Source: Microsoft, Synopsys, Baya Systems, ANSYS

Microsoft's Asks to the Ecosystem



Industry Standards

Industry collaboration on standardization

System Interfaces

Rack formats and other components

Innovation & IP Reuse/Integration

Customization is justified if it significantly improves KPI

Use Cases Drive Reconfigurability & Modularity

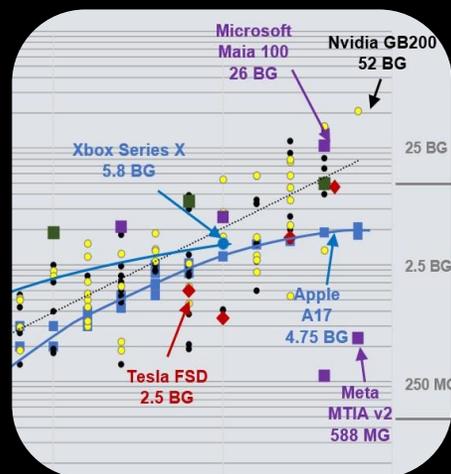
Compounding Complexities

Hardware-assisted Verification (HAV): The Keystone for Ensuring Functionality, Power and Performance

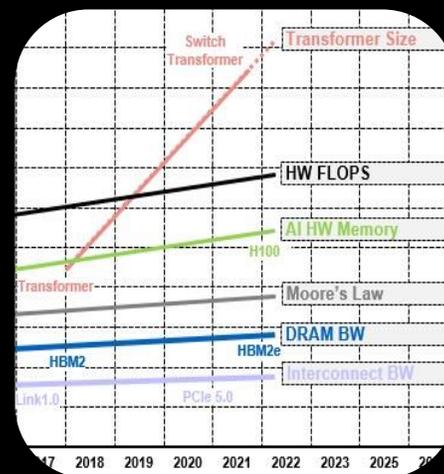
Software



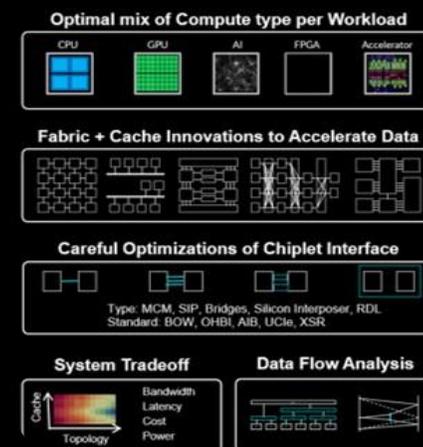
Hardware



Interfaces



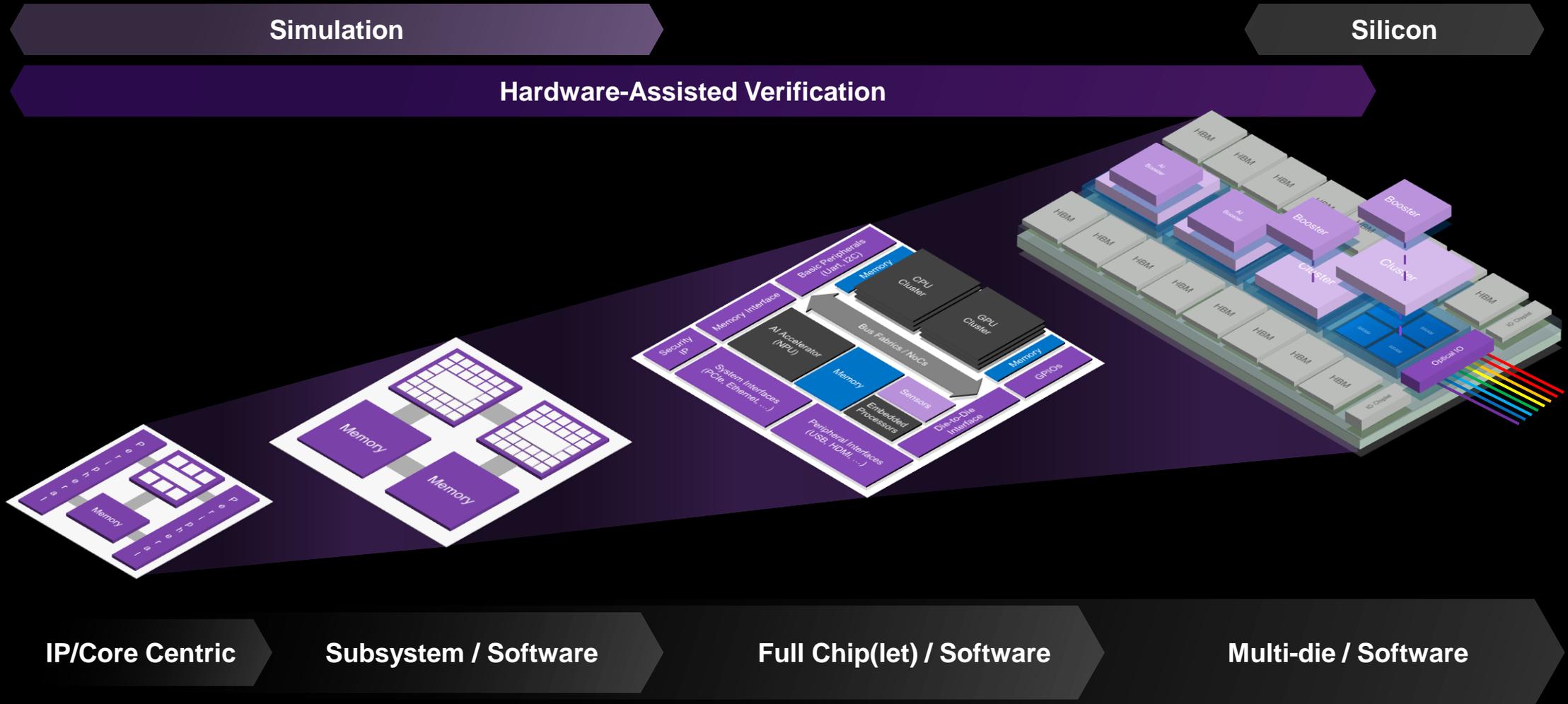
Architectures



Verification Challenge: **Quadrillions of Cycles***

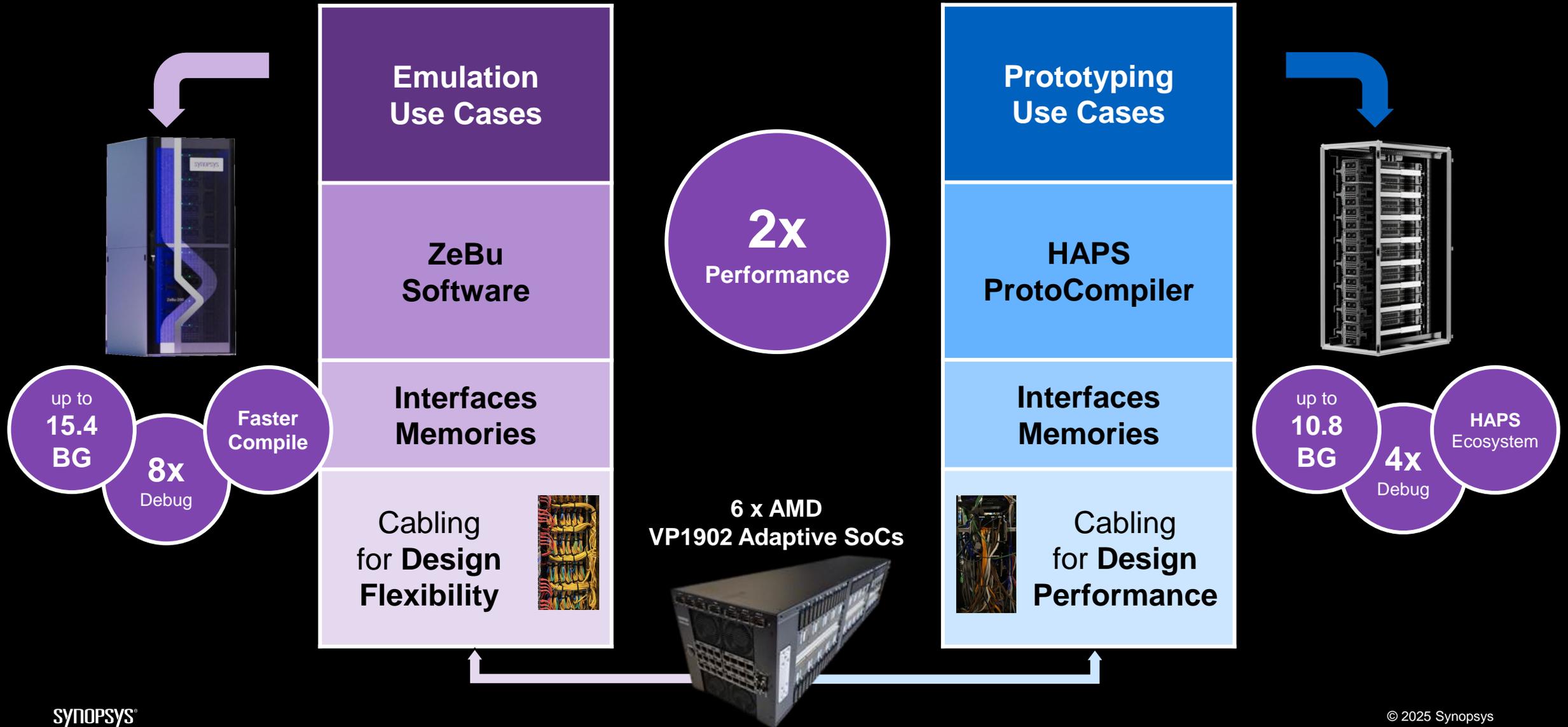
Verification needs Quadrillions of Cycles!

From ISA Through CPU, Clusters of CPUs and Systems on Chips / of Chiplets



Configurability for EP-Ready Hardware

Enabling Different Hardware/Software Stacks optimized for Emulation and Prototyping





Emulation
Cabling
for **Design
Flexibility**

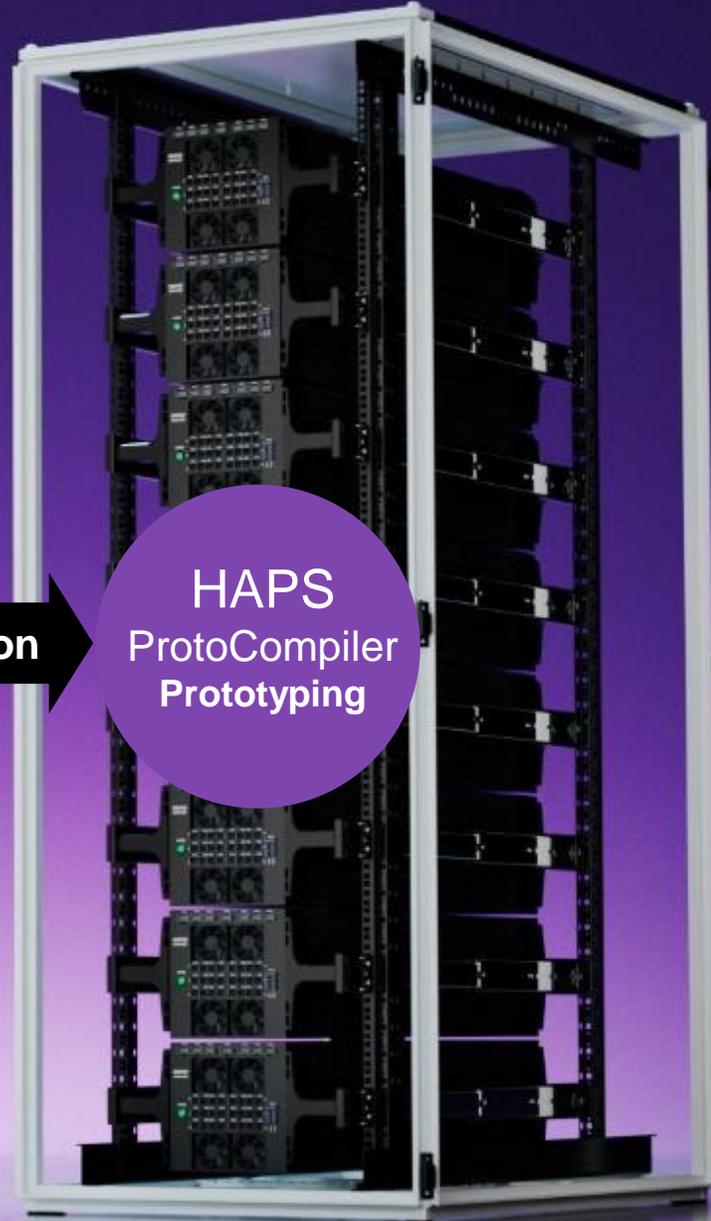
synopsys®



ZeBu-200

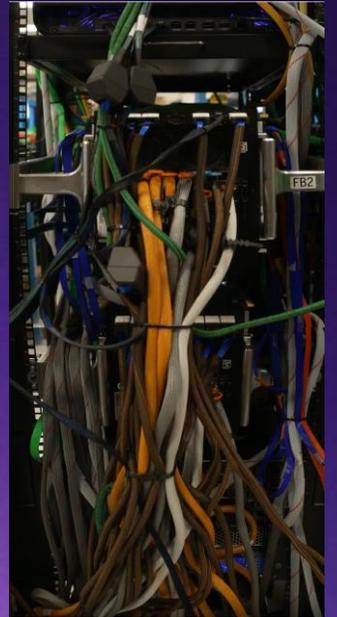
**ZeBu
Software
Emulation**

EP SW Transition



HAPS-200

**HAPS
ProtoCompiler
Prototyping**



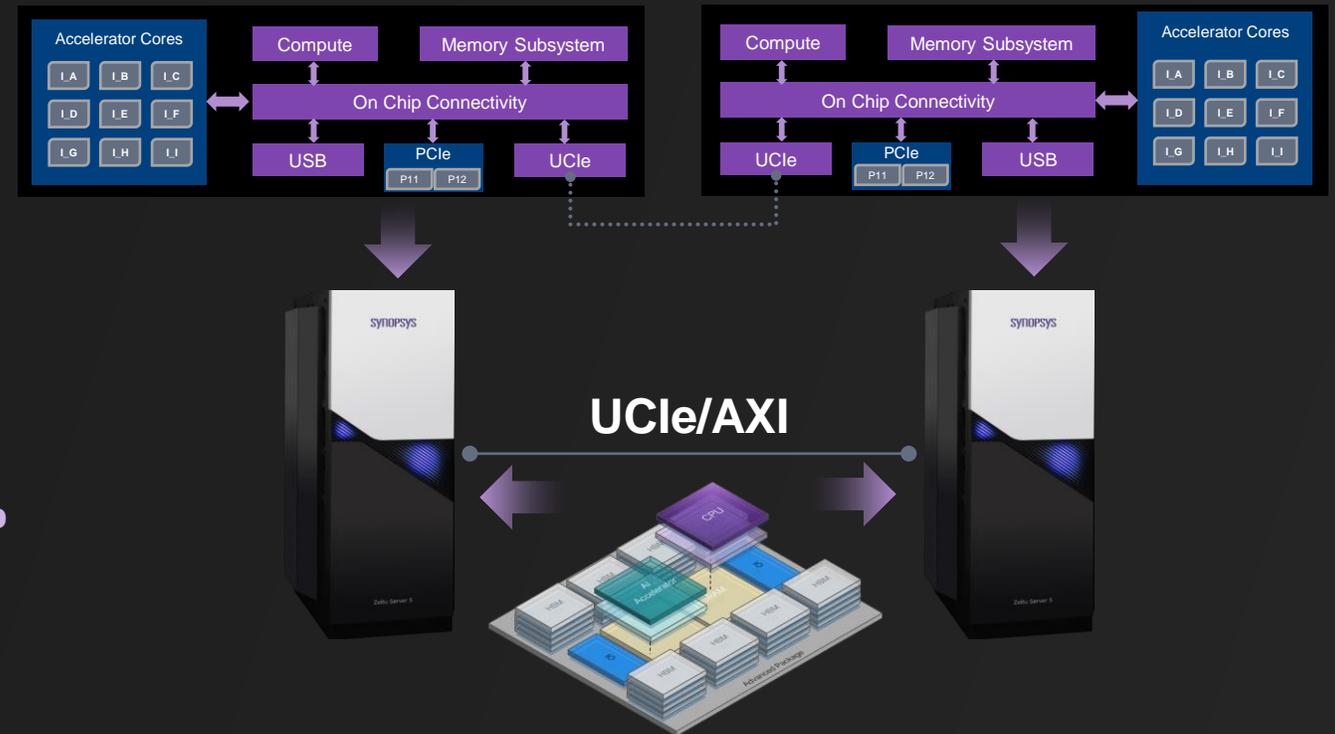
Prototyping
Cabling
for **Design
Performance**

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Vision to future HPC/Data Center Needs

Modular Verification and Optimization for Sub-system Reuse

- Scale for **large multi-chiplet systems**
 - **Standard interfaces**
 - Reduces **time-to-model**
 - Extends **scalability** to beyond 60BG
- Arm CSS Integration
 - Pre-validated **integration with Synopsys IP**
 - Arm CSS-Ready Silicon to Systems Design
 - Save up to 80 man-years / 18 month



arm

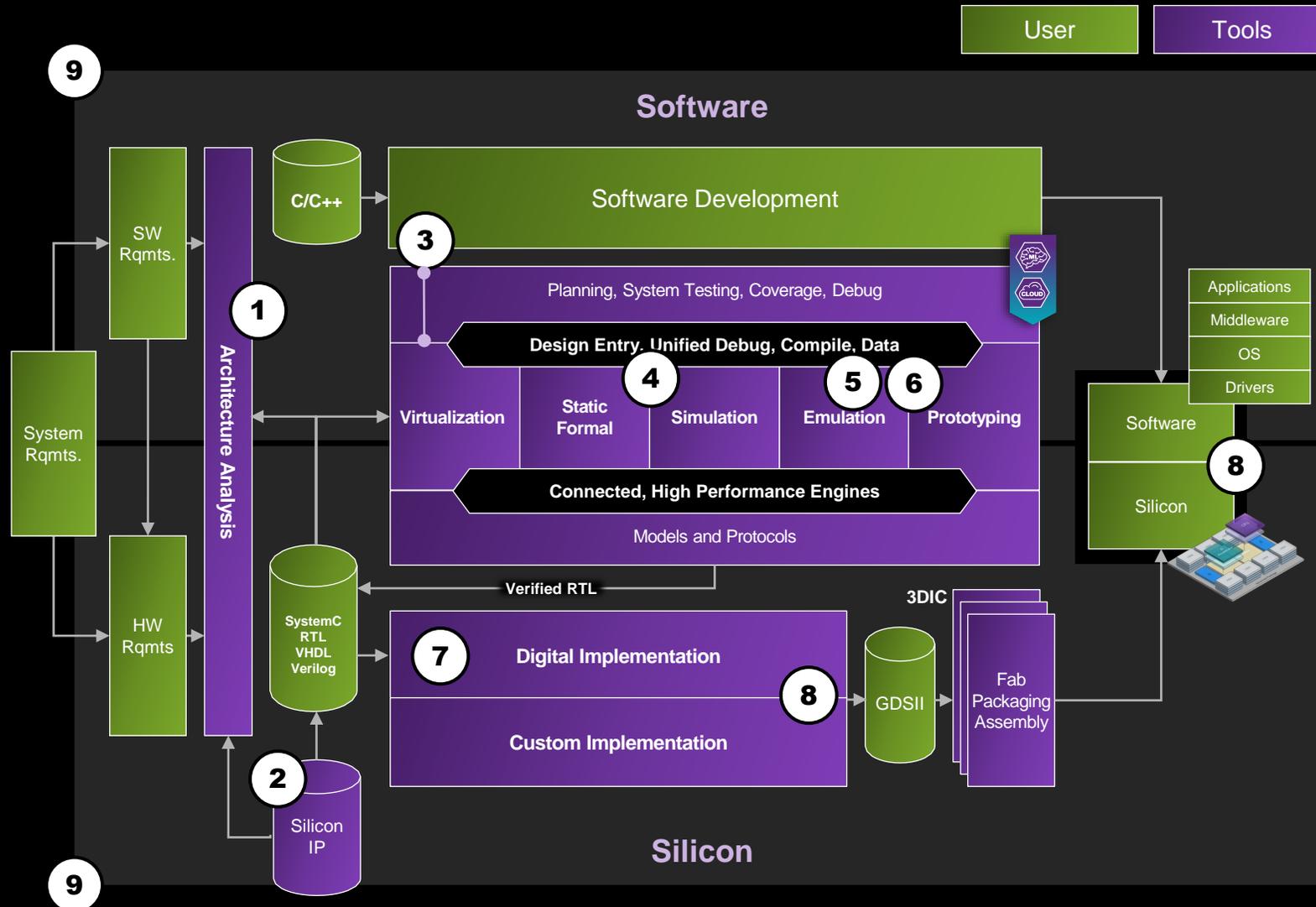
“Synopsys is a **key member of Arm Total Design**, bringing **critical tools and the advanced HAV capabilities** to quickly and **reliably validate** solutions built on **Arm Compute Subsystems (CSS)**,”

Kevo Kechichian, Executive Vice President, Solutions Engineering, Arm

Putting it all together into a flow

A Silicon to Systems Design Flow

The North Star for Arm CSS Integration



- 1 Architecture Analysis for Arm CSS
- 2 Arm CSS-Ready IP Portfolio
- 3 Virtual Prototypes for Arm CSS SW Dev
- 4 Arm CSS/IP/VIP Integration Verification
- 5 Arm CSS in System V&V, Perf, Power
- 6 Arm CSS SW at high fidelity (Emu/Proto)
- 7 Arm CSS PPA Optimization
- 8 Silicon Lifecycle Management
- 9 Expertise & Services

Hardware-Assisted Verification Solutions

Use Cases from HW/SW through Verification to Compliance



Early RTL Verification

Verdi & VCS

Highest Scalability
Best Density

Power/
Performance
Analysis



Platform Architect

Test	P/F
1	✓
2	✓
3	✗
4	✓

RTL Regression

Software/
Hardware
Validation



HAPS Protocol Interface Card



Speed Adaptor



Software Bring-up

Virtualizer

Highest Performance
EP-Ready Hardware

Compliance/
Certification



HAPS IP Prototyping Kit

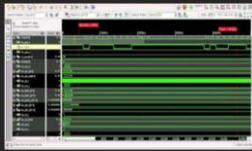
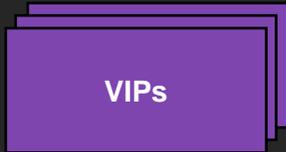


Unified Core Technologies: Compile, Debug, Hybrid, Transactors

Protocol Solutions for all Use Cases

PCIe, CXL, USB, HBM, UCIe, ...

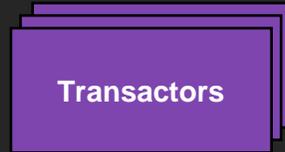
Exhaustive IP / Protocol Verification



VCS

- IP & Blocks
- New Protocols
- UVM Coverage Closure

Virtual Traffic from Scalable Interfaces



ZS5 or ZeBu EP1/2

- SoC-level
- New Protocols
- HW/SW Bring-up
- Performance & Power
- SW/HW

Rate-adapted Traffic from Real Interfaces



ZS5, ZeBu EP1/2, HAPS-100

- HW/SW Bring-up with high fidelity
- Drivers
- Interoperability

At-speed Traffic from Real Interfaces

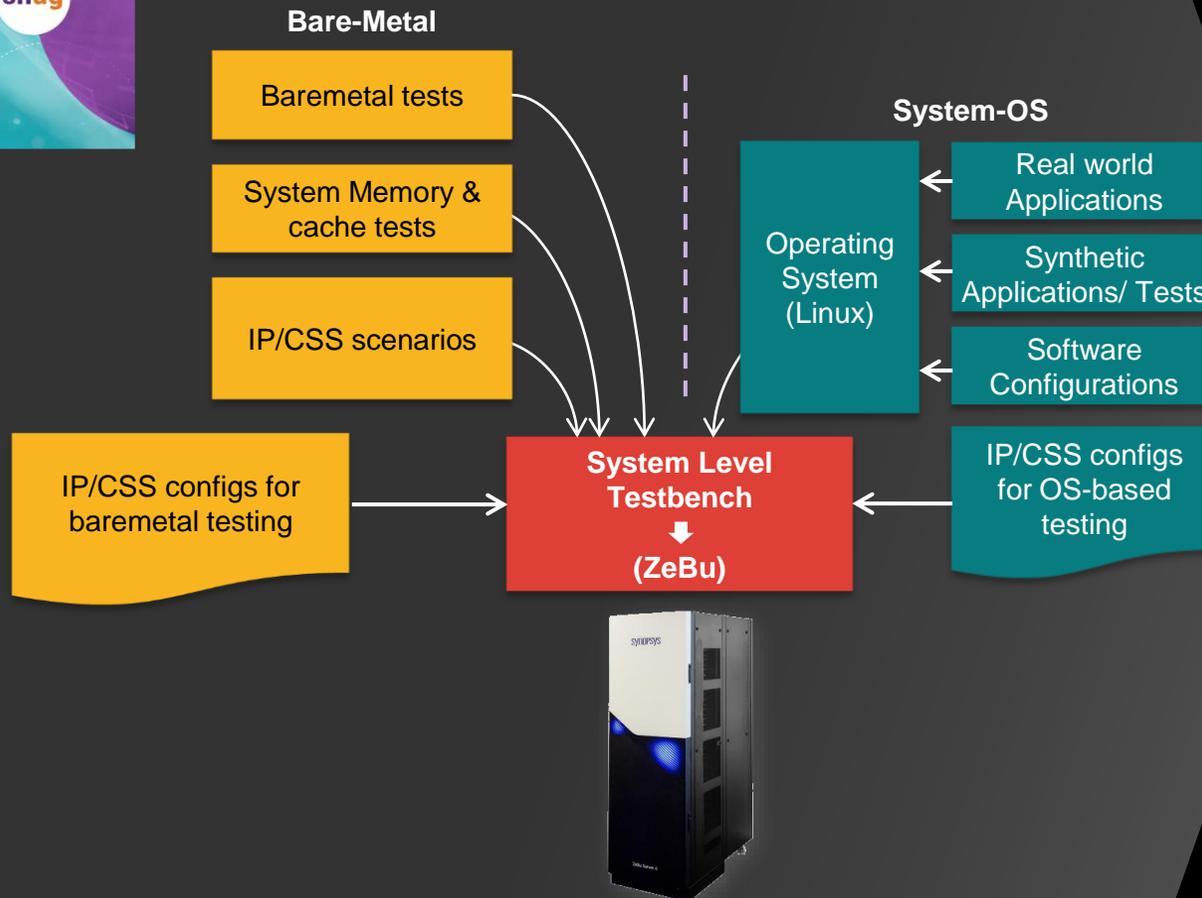


ZeBu EP1/2 or HAPS-100

- Controller + PHY Integration
- Driver Compliance
- Protocol IP Certification
- At-Speed Interoperability Testing

Example: Arm

SW Workloads Driving Performance & Low Power Analysis



Performance analysis
Coverage closure
Meet SW targets

Low Power Optimization with Real AI Workloads

Fastest Power Profiling for Real Software Workloads

Key Benefits

Large designs, Realistic workloads,
Multiple iterations per day

Actionable power profiling for
dynamic and leakage power

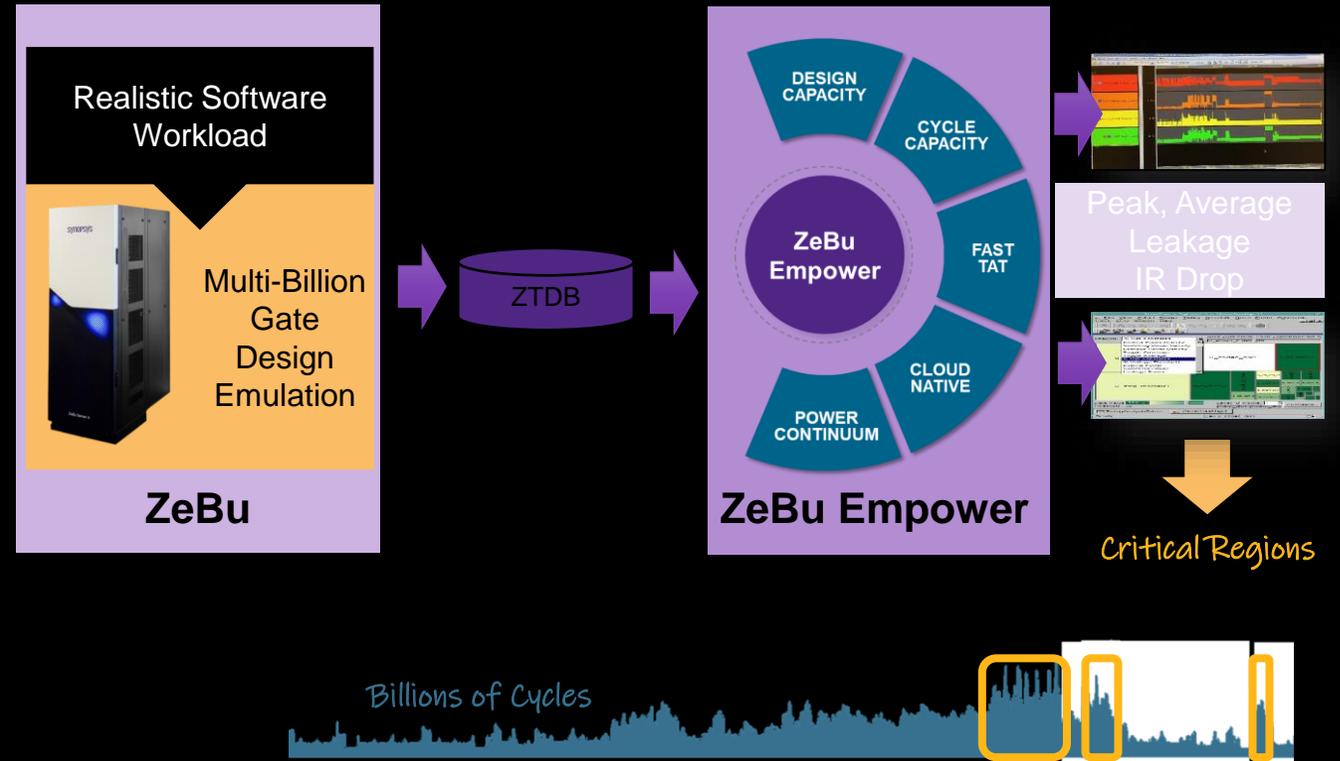
Power critical blocks and vectors
feeding into signoff analysis

“ZeBu Empower’s impressive performance provides our design teams with a global perspective on power, leading them to the key areas for optimization.”

SiMaai™

Krishna Rangasayee
Founder and CEO

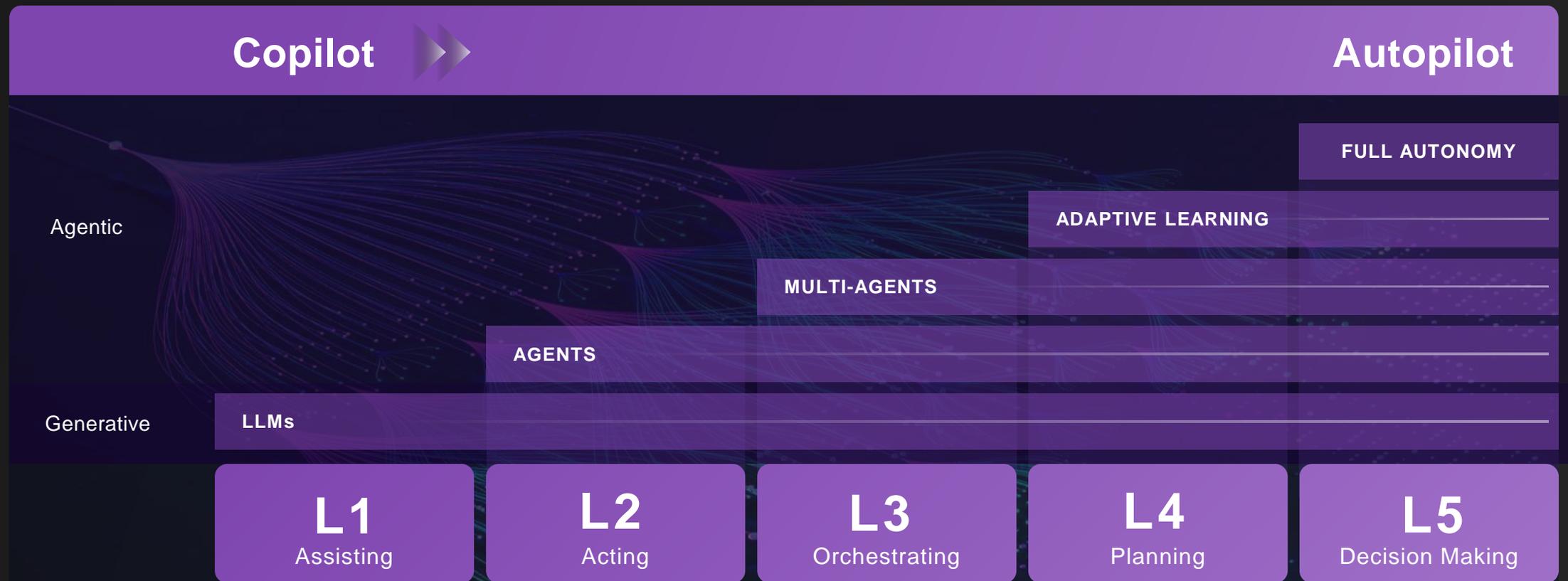
Power Emulation



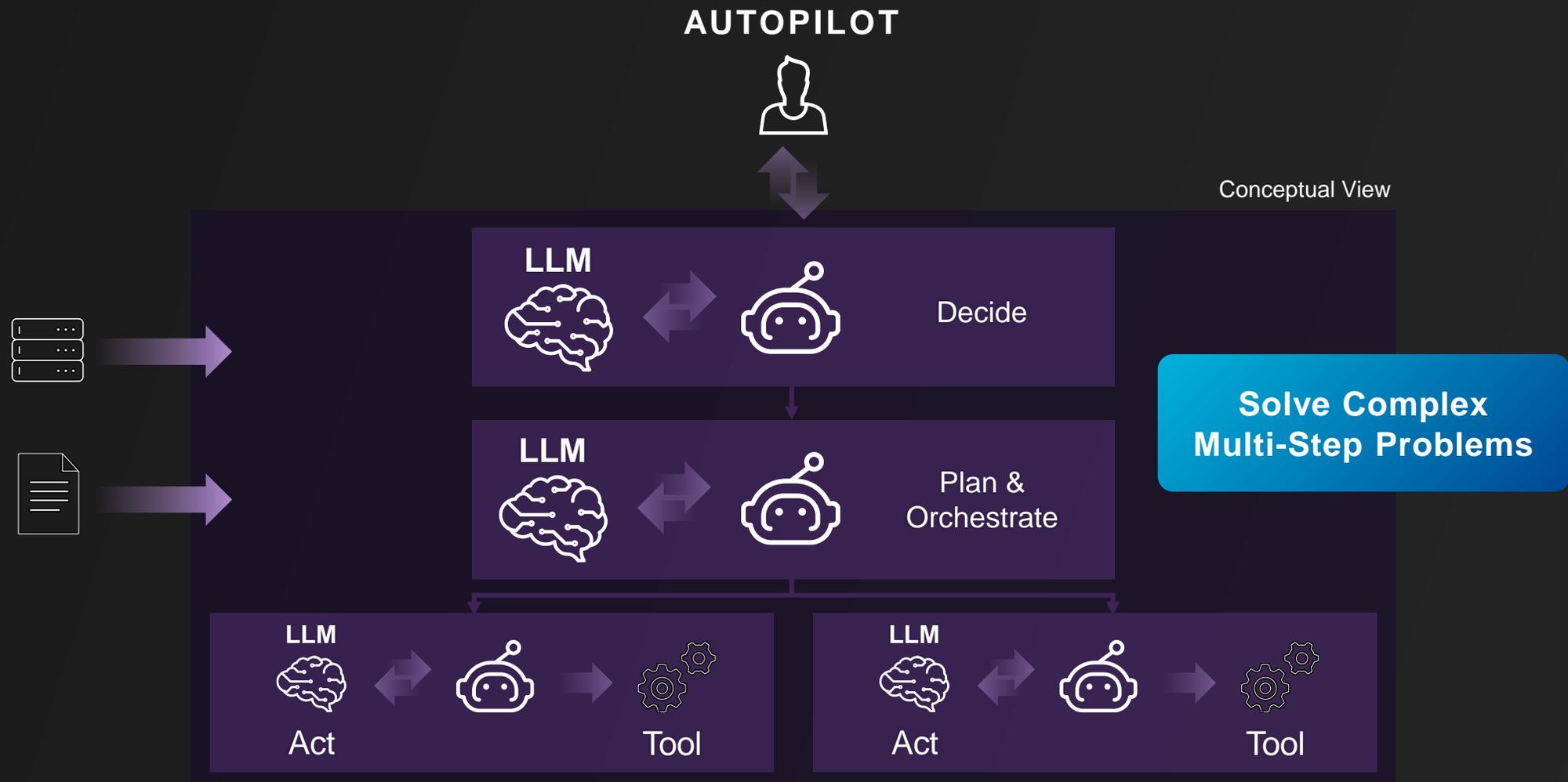
Hardware and Software Architected for Maximum Compute Throughput

AI For Productivity Improvements

Vision: AI Powered Engineering Workflows



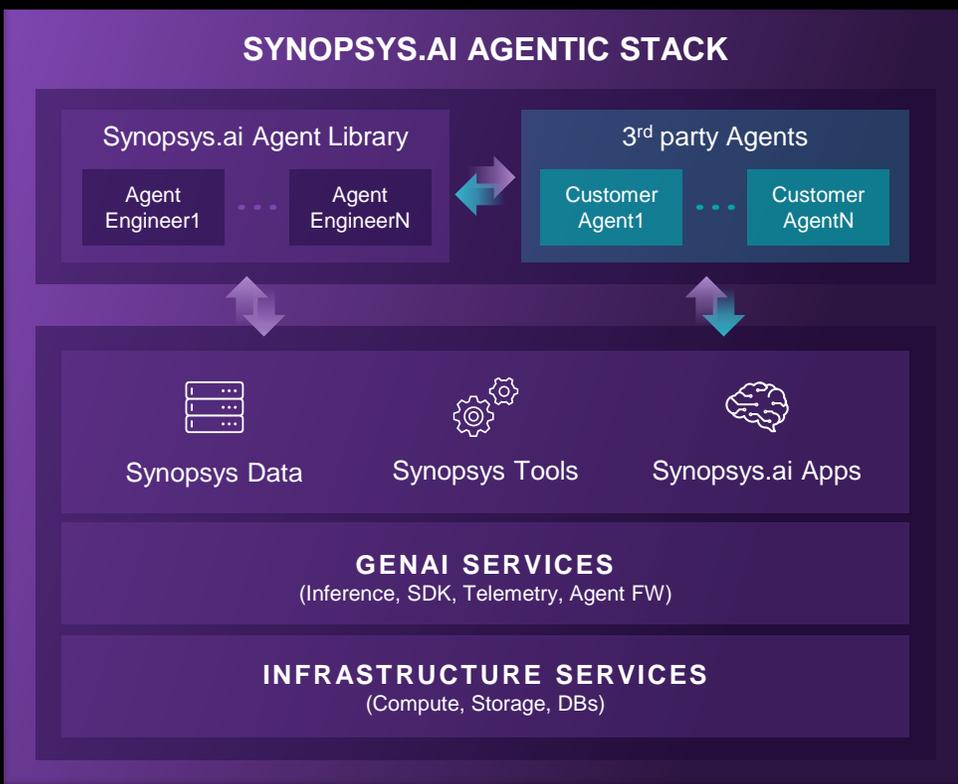
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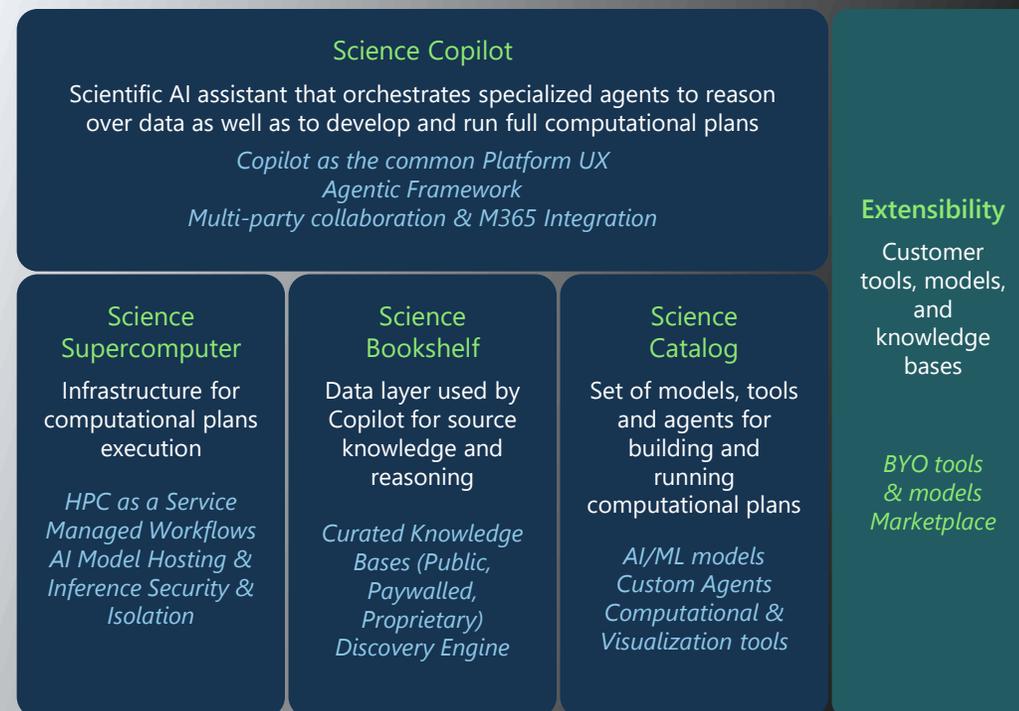
SNPS – MSFT Joint Partnership

Transforming engineering innovation into business success, together.

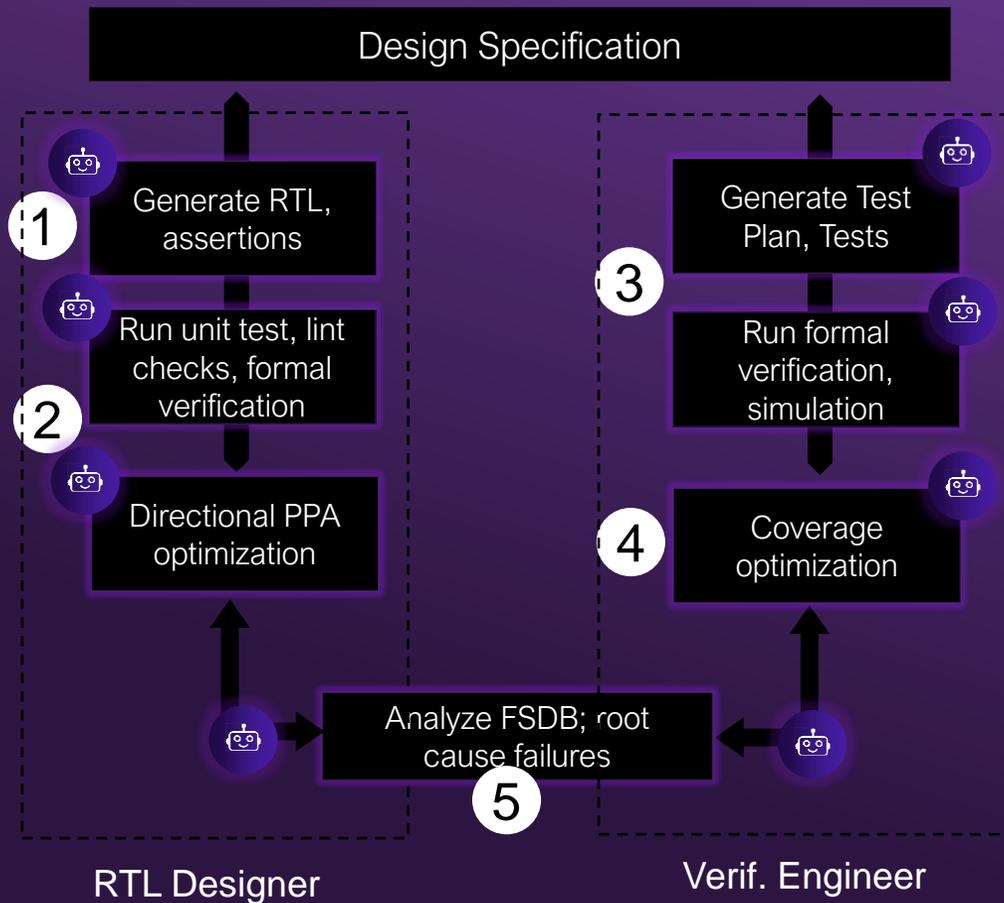
SYNOPTSYS.AI AGENTIC STACK



Microsoft Discovery Platform



Synopsys.ai: AI Optimization and Assistants for Design and Verification



AI Apps for Verif HVPs

RTL Assistant

1 Code Advisor

2 Lint Advisor, Formal Advisor, PPA Advisor, Unit Test

Verif. Assistant

3 Spec2Testplan*, Spec2TB*, Formal Advisor

4 VSO.ai (ML)

Debug Assistant

5 Verdi Assistant, RDA (ML)

* - WIP

Outlook: Where do we go from here?

Re-engineering intelligent systems

AI model development

LLM training & inference,
reasoning models

Software development

OS, middleware, application, web

Silicon development

providing required performance
with lowest power usage



Electrical design

reliability, PCB, power supply efficiency

Fluids

airflow

Mechanical design

stress forces, interconnect

Thermal design

heating/cooling

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Thank you